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# SAM7S512 SAM7S256 SAM7S128 SAM7S64 SAM7S321 SAM7S32 SAM7S161 SAM7S16

#### **Features**

- Incorporates the ARM7TDMI® ARM® Thumb® Processor
  - High-performance 32-bit RISC Architecture
  - High-density 16-bit Instruction Set
  - Leader in MIPS/Watt
  - EmbeddedICE<sup>™</sup> In-circuit Emulation, Debug Communication Channel Support
- Internal High-speed Flash
  - 512 Kbytes (SAM7S512) Organized in Two Contiguous Banks of 1024 Pages of 256 Bytes (Dual Plane)
  - 256 Kbytes (SAM7S256) Organized in 1024 Pages of 256 Bytes (Single Plane)
  - 128 Kbytes (SAM7S128) Organized in 512 Pages of 256 Bytes (Single Plane)
  - 64 Kbytes (SAM7S64) Organized in 512 Pages of 128 Bytes (Single Plane)
  - 32 Kbytes (SAM7S321/32) Organized in 256 Pages of 128 Bytes (Single Plane)
  - 16 Kbytes (SAM7S161/16) Organized in 256 Pages of 64 Bytes (Single Plane)
  - Single Cycle Access at Up to 30 MHz in Worst Case Conditions
  - Prefetch Buffer Optimizing Thumb Instruction Execution at Maximum Speed
  - Page Programming Time: 6 ms, Including Page Auto-erase, Full Erase Time: 15 ms
  - 10,000 Write Cycles, 10-year Data Retention Capability, Sector Lock Capabilities, Flash Security Bit
  - Fast Flash Programming Interface for High Volume Production
- Internal High-speed SRAM, Single-cycle Access at Maximum Speed
  - 64 Kbytes (SAM7S512/256)
  - 32 Kbytes (SAM7S128)
  - 16 Kbytes (SAM7S64)
  - 8 Kbytes (SAM7S321/32)
  - 4 Kbytes (SAM7S161/16)
- Memory Controller (MC)
  - Embedded Flash Controller, Abort Status and Misalignment Detection
- Reset Controller (RSTC)
  - Based on Power-on Reset and Low-power Factory-calibrated Brown-out Detector
  - Provides External Reset Signal Shaping and Reset Source Status
- Clock Generator (CKGR)
  - Low-power RC Oscillator, 3 to 20 MHz On-chip Oscillator and one PLL
- Power Management Controller (PMC)
  - Software Power Optimization Capabilities, Including Slow Clock Mode (Down to 500 Hz) and Idle Mode
  - Three Programmable External Clock Signals
- Advanced Interrupt Controller (AIC)
  - Individually Maskable, Eight-level Priority, Vectored Interrupt Sources
  - Two (SAM7S512/256/128/64/321/161) or One (SAM7S32/16) External Interrupt Source(s) and One Fast Interrupt Source, Spurious Interrupt Protected

- Debug Unit (DBGU)
  - 2-wire UART and Support for Debug Communication Channel interrupt, Programmable ICE Access Prevention
  - Mode for General Purpose 2-wire UART Serial Communication
- Periodic Interval Timer (PIT)
  - 20-bit Programmable Counter plus 12-bit Interval Counter
- Windowed Watchdog (WDT)
  - 12-bit key-protected Programmable Counter
  - Provides Reset or Interrupt Signals to the System
  - Counter May Be Stopped While the Processor is in Debug State or in Idle Mode
- · Real-time Timer (RTT)
  - 32-bit Free-running Counter with Alarm
  - Runs Off the Internal RC Oscillator
- One Parallel Input/Output Controller (PIOA)
  - Thirty-two (SAM7S512/256/128/64/321/161) or twenty-one (SAM7S32/16) Programmable I/O Lines Multiplexed with up to Two Peripheral I/Os
  - Input Change Interrupt Capability on Each I/O Line
  - Individually Programmable Open-drain, Pull-up resistor and Synchronous Output
- Eleven (SAM7S512/256/128/64/321/161) or Nine (SAM7S32/16) Peripheral DMA Controller (PDC) Channels
- One USB 2.0 Full Speed (12 Mbits per Second) Device Port (Except for the SAM7S32/16).
  - On-chip Transceiver, 328-byte Configurable Integrated FIFOs
- One Synchronous Serial Controller (SSC)
  - Independent Clock and Frame Sync Signals for Each Receiver and Transmitter
  - I2S Analog Interface Support, Time Division Multiplex Support
  - High-speed Continuous Data Stream Capabilities with 32-bit Data Transfer
- Two (SAM7S512/256/128/64/321/161) or One (SAM7S32/16) Universal Synchronous/Asynchronous Receiver Transmitters (USART)
  - Individual Baud Rate Generator, IrDA® Infrared Modulation/Demodulation
  - Support for ISO7816 T0/T1 Smart Card, Hardware Handshaking, RS485 Support
  - Full Modem Line Support on USART1 (SAM7S512/256/128/64/321/161)
- One Master/Slave Serial Peripheral Interface (SPI)
  - 8- to 16-bit Programmable Data Length, Four External Peripheral Chip Selects
- One Three-channel 16-bit Timer/Counter (TC)
  - Three External Clock Input and Two Multi-purpose I/O Pins per Channel (SAM7S512/256/128/64/321/161)
  - One External Clock Input and Two Multi-purpose I/O Pins for the first Two Channels Only (SAM7S32/16)
  - Double PWM Generation, Capture/Waveform Mode, Up/Down Capability
- One Four-channel 16-bit PWM Controller (PWMC)
- · One Two-wire Interface (TWI)
  - Master Mode Support Only, All Two-wire Atmel EEPROMs and I<sup>2</sup>C Compatible Devices Supported (SAM7S512/256/128/64/321/32)
  - Master, Multi-Master and Slave Mode Support, All Two-wire Atmel EEPROMs and I<sup>2</sup>C Compatible Devices Supported (SAM7S161/16)
- One 8-channel 10-bit Analog-to-Digital Converter, Four Channels Multiplexed with Digital I/Os
- SAM-BA<sup>™</sup> Boot Assistant
  - Default Boot program
  - Interface with SAM-BA Graphic User Interface
- IEEE® 1149.1 JTAG Boundary Scan on All Digital Pins
- 5V-tolerant I/Os, including Four High-current Drive I/O lines, Up to 16 mA Each (SAM7S161/16 I/Os Not 5V-tolerant)
- Power Supplies
  - Embedded 1.8V Regulator, Drawing up to 100 mA for the Core and External Components
  - 3.3V or 1.8V VDDIO I/O Lines Power Supply, Independent 3.3V VDDFLASH Flash Power Supply
  - 1.8V VDDCORE Core Power Supply with Brown-out Detector



- Fully Static Operation: Up to 55 MHz at 1.65V and 85°C Worst Case Conditions
- Available in 64-lead LQFP Green or 64-pad QFN Green Package (SAM7S512/256/128/64/321/161) and 48-lead LQFP Green or 48-pad QFN Green Package (SAM7S32/16)

# 1. Description

Atmel's SAM7S is a series of low pincount Flash microcontrollers based on the 32-bit ARM RISC processor. It features a high-speed Flash and an SRAM, a large set of peripherals, including a USB 2.0 device (except for the SAM7S32 and SAM7S16), and a complete set of system functions minimizing the number of external components. The device is an ideal migration path for 8-bit microcontroller users looking for additional performance and extended memory.

The embedded Flash memory can be programmed in-system via the JTAG-ICE interface or via a parallel interface on a production programmer prior to mounting. Built-in lock bits and a security bit protect the firmware from accidental overwrite and preserves its confidentiality.

The SAM7S Series system controller includes a reset controller capable of managing the power-on sequence of the microcontroller and the complete system. Correct device operation can be monitored by a built-in brownout detector and a watchdog running off an integrated RC oscillator.

The SAM7S Series are general-purpose microcontrollers. Their integrated USB Device port makes them ideal devices for peripheral applications requiring connectivity to a PC or cellular phone. Their aggressive price point and high level of integration pushes their scope of use far into the cost-sensitive, high-volume consumer market.

# 1.1 Configuration Summary of the SAM7S512, SAM7S256, SAM7S128, SAM7S64, SAM7S321, SAM7S32, SAM7S161 and SAM7S16

The SAM7S512, SAM7S256, SAM7S128, SAM7S64, SAM7S321, SAM7S32, SAM7S161 and SAM7S16 differ in memory size, peripheral set and package. Table 1-1 summarizes the configuration of the six devices.

Except for the SAM7S32/16, all other SAM7S devices are package and pinout compatible.

Table 1-1. Configuration Summary

Device	Flash	TWI	Flash Organization	SRAM	USB Device Port	USART	External Interrupt Source		TC Channels	I/O 5V Tolerant	I/O Lines	Package
SAM7S512	512 Kbytes	Master	dual plane	64 Kbytes	1	2 <sup>(1) (2)</sup>	2	11	3	Yes	32	LQFP/ QFN 64
SAM7S256	256 Kbytes	Master	single plane	64 Kbytes	1	2 <sup>(1)</sup> (2)	2	11	3	Yes	32	LQFP/ QFN 64
SAM7S128	128 Kbytes	Master	single plane	32 Kbytes	1	2 <sup>(1)</sup> (2)	2	11	3	Yes	32	LQFP/ QFN 64
SAM7S64	64 Kbytes	Master	single plane	16 Kbytes	1	2 <sup>(2)</sup>	2	11	3	Yes	32	LQFP/ QFN 64
SAM7S321	32 Kbytes	Master	single plane	8 Kbytes	1	2 <sup>(2)</sup>	2	11	3	Yes	32	LQFP/ QFN 64
SAM7S32	32 Kbytes	Master	single plane	8 Kbytes	not present	1	1	9	3 <sup>(3)</sup>	Yes	21	LQFP/ QFN 48
SAM7S161	16 Kbytes	Master/ Slave	single plane	4 Kbytes	1	2 <sup>(2)</sup>	2	11	3	No	32	LQFP
SAM7S16	16 Kbytes	Master/ Slave	single plane	4 Kbytes	not present	1	1	9	3 <sup>(3)</sup>	No	21	LQFP/ QFN 48

Notes: 1. Fractional Baud Rate.

- 2. Full modem line support on USART1.
- 3. Only two TC channels are accessible through the PIO.



# 2. Block Diagram

Figure 2-1. SAM7S512/256/128/64/321/161 Block Diagram

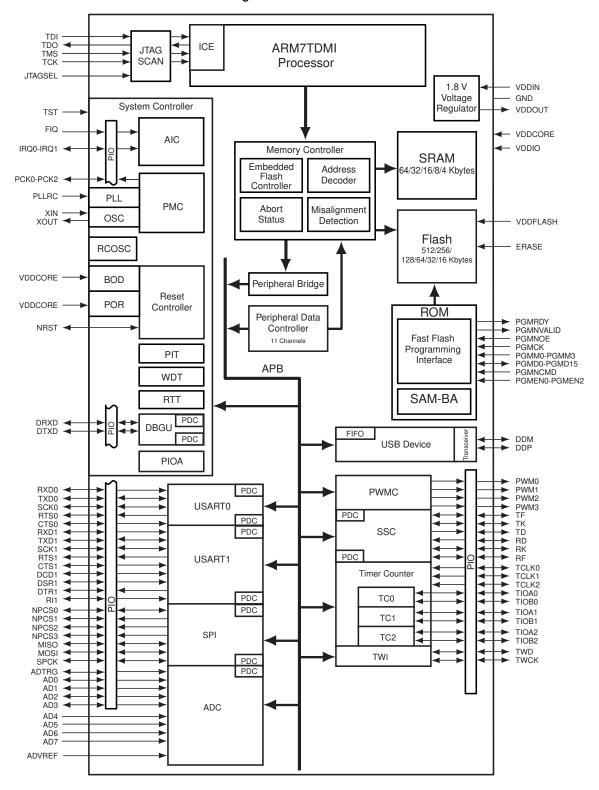
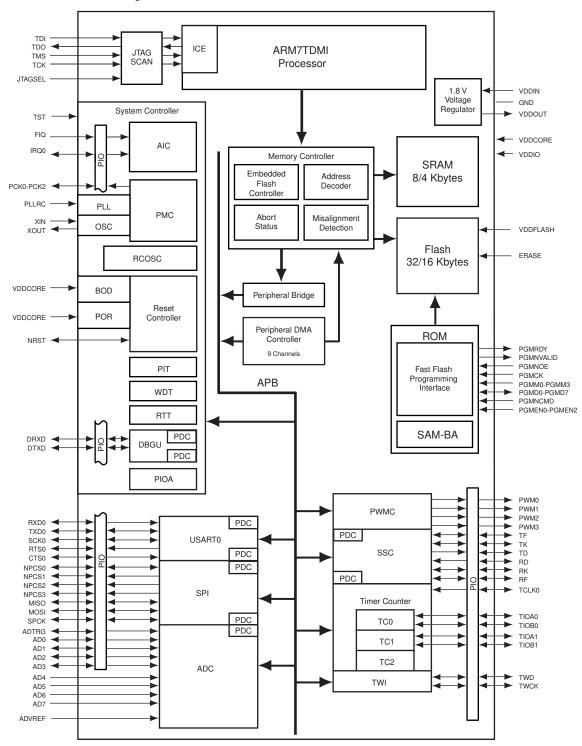




Figure 2-2. SAM7S32/16 Block Diagram





# 3. Signal Description

Table 3-1. Signal Description List

Signal Name	Function	Туре	Active Level	Comments
-	Po	wer		
VDDIN	Voltage and ADC Regulator Power Supply Input	Power		3.0 to 3.6V
VDDOUT	Voltage Regulator Output	Power		1.85V nominal
VDDFLASH	Flash Power Supply	Power		3.0V to 3.6V
VDDIO	I/O Lines Power Supply	Power		3.0V to 3.6V or 1.65V to 1.95V
VDDCORE	Core Power Supply	Power		1.65V to 1.95V
VDDPLL	PLL	Power		1.65V to 1.95V
GND	Ground	Ground		
	Clocks, Oscilla	ators and PL	Ls	
XIN	Main Oscillator Input	Input		
XOUT	Main Oscillator Output	Output		
PLLRC	PLL Filter	Input		
PCK0 - PCK2	Programmable Clock Output	Output		
	ICE and	d JTAG	1	
TCK	Test Clock	Input		No pull-up resistor
TDI	Test Data In	Input		No pull-up resistor
TDO	Test Data Out	Output		
TMS	Test Mode Select	Input		No pull-up resistor
JTAGSEL	JTAG Selection	Input		Pull-down resistor <sup>(1)</sup>
	Flash N	<b>l</b> lemory		
ERASE	Flash and NVM Configuration Bits Erase Command	Input	High	Pull-down resistor <sup>(1)</sup>
	Rese	t/Test	•	
NRST	Microcontroller Reset	I/O	Low	Open-drain with pull-Up resistor
TST	Test Mode Select	Input	High	Pull-down resistor <sup>(1)</sup>
	Debu	g Unit	•	
DRXD	Debug Receive Data	Input		
DTXD	Debug Transmit Data	Output		
	A	iC	•	
IRQ0 - IRQ1	External Interrupt Inputs	Input		IRQ1 not present on SAM7S32/16
FIQ	Fast Interrupt Input	Input		
	P	Ю		
PA0 - PA31	Parallel IO Controller A	I/O		Pulled-up input at reset PA0 - PA20 only on SAM7S32/16



Table 3-1. Signal Description List (Continued)

Oi	Function	T	Active	0
Signal Name	Function	Туре	Level	Comments
		Device Port	Ι	
DDM	USB Device Port Data -	Analog		not present on SAM7S32/16
DDP	USB Device Port Data +	Analog		not present on SAM7S32/16
		USART	ı	
SCK0 - SCK1	Serial Clock	I/O		SCK1 not present on SAM7S32/16
TXD0 - TXD1	Transmit Data	I/O		TXD1 not present on SAM7S32/16
RXD0 - RXD1	Receive Data	Input		RXD1 not present on SAM7S32/16
RTS0 - RTS1	Request To Send	Output		RTS1 not present on SAM7S32/16
CTS0 - CTS1	Clear To Send	Input		CTS1 not present on SAM7S32/16
DCD1	Data Carrier Detect	Input		not present on SAM7S32/16
DTR1	Data Terminal Ready	Output		not present on SAM7S32/16
DSR1	Data Set Ready	Input		not present on SAM7S32/16
RI1	Ring Indicator	Input		not present on SAM7S32/16
	Synchrono	us Serial Contro	ller	
TD	Transmit Data	Output		
RD	Receive Data	Input		
TK	Transmit Clock	I/O		
RK	Receive Clock	I/O		
TF	Transmit Frame Sync	I/O		
RF	Receive Frame Sync	I/O		
	Tim	ner/Counter		
TCLK0 - TCLK2	External Clock Inputs	Input		TCLK1 and TCLK2 not present on SAM7S32/16
TIOA0 - TIOA2	I/O Line A	I/O		TIOA2 not present on SAM7S32/16
TIOB0 - TIOB2	I/O Line B	I/O		TIOB2 not present on SAM7S32/16
	PWI	M Controller		
PWM0 - PWM3	PWM Channels	Output		
	•	SPI		•
MISO	Master In Slave Out	I/O		
MOSI	Master Out Slave In	I/O		
SPCK	SPI Serial Clock	I/O		
NPCS0	SPI Peripheral Chip Select 0	I/O	Low	
NPCS1-NPCS3	SPI Peripheral Chip Select 1 to 3	Output	Low	



Table 3-1. Signal Description List (Continued)

Signal Name	Function	Туре	Active Level	Comments
	Two-Wi	re Interface	•	•
TWD	Two-wire Serial Data	I/O		
TWCK	Two-wire Serial Clock	I/O		
	Analog-to-D	igital Convert	er	
AD0-AD3	Analog Inputs	Analog		Digital pulled-up inputs at reset
AD4-AD7	Analog Inputs	Analog		Analog Inputs
ADTRG	ADC Trigger	Input		
ADVREF	ADC Reference	Analog		
	Fast Flash Prog	ramming Inte	rface	
PGMEN0-PGMEN2	Programming Enabling	Input		
PGMM0-PGMM3	Programming Mode	Input		
PGMD0-PGMD15	Programming Data	I/O		PGMD0-PGMD7 only on SAM7S32/16
PGMRDY	Programming Ready	Output	High	
PGMNVALID	Data Direction	Output	Low	
PGMNOE	Programming Read	Input	Low	
PGMCK	Programming Clock	Input		
PGMNCMD	Programming Command	Input	Low	

Note: 1. Refer to Section 6. "I/O Lines Considerations" on page 14.



# 4. Package and Pinout

The SAM7S512/256/128/64/321 are available in a 64-lead LQFP or 64-pad QFN package.

The SAM7S161 is available in a 64-Lead LQFP package.

The SAM7S32/16 are available in a 48-lead LQFP or 48-pad QFN package.

## 4.1 64-lead LQFP and 64-pad QFN Package Outlines

Figure 4-1 and Figure 4-2 show the orientation of the 64-lead LQFP and the 64-pad QFN package. A detailed mechanical description is given in the section Mechanical Characteristics of the full datasheet.

Figure 4-1. 64-lead LQFP Package (Top View)

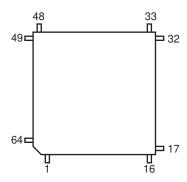
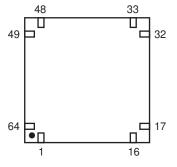


Figure 4-2. 64-pad QFN Package (Top View)





# 4.2 64-lead LQFP and 64-pad QFN Pinout

Table 4-1. SAM7S512/256/128/64/321/161 Pinout<sup>(1)</sup>

1	ADVREF
2	GND
3	AD4
4	AD5
5	AD6
6	AD7
7	VDDIN
8	VDDOUT
9	PA17/PGMD5/AD0
10	PA18/PGMD6/AD1
11	PA21/PGMD9
12	VDDCORE
13	PA19/PGMD7/AD2
14	PA22/PGMD10
15	PA23/PGMD11
16	PA20/PGMD8/AD3

17	GND
18	VDDIO
19	PA16/PGMD4
20	PA15/PGMD3
21	PA14/PGMD2
22	PA13/PGMD1
23	PA24/PGMD12
24	VDDCORE
25	PA25/PGMD13
26	PA26/PGMD14
27	PA12/PGMD0
28	PA11/PGMM3
29	PA10/PGMM2
30	PA9/PGMM1
31	PA8/PGMM0
32	PA7/PGMNVALID
7	

33	TDI
34	PA6/PGMNOE
35	PA5/PGMRDY
36	PA4/PGMNCMD
37	PA27/PGMD15
38	PA28
39	NRST
40	TST
41	PA29
42	PA30
43	PA3
44	PA2/PGMEN2
45	VDDIO
46	GND
47	PA1/PGMEN1
48	PA0/PGMEN0

49	TDO
50	JTAGSEL
51	TMS
52	PA31
53	TCK
54	VDDCORE
55	ERASE
56	DDM
57	DDP
58	VDDIO
59	VDDFLASH
60	GND
61	XOUT
62	XIN/PGMCK
63	PLLRC
64	VDDPLL

Note: 1. The bottom pad of the QFN package must be connected to ground.



# 4.3 48-lead LQFP and 48-pad QFN Package Outlines

Figure 4-3 and Figure 4-4 show the orientation of the 48-lead LQFP and the 48-pad QFN package. A detailed mechanical description is given in the section Mechanical Characteristics of the full datasheet.

Figure 4-3. 48-lead LQFP Package (Top View)

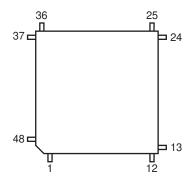
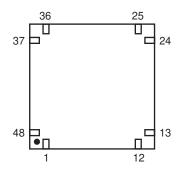


Figure 4-4. 48-pad QFN Package (Top View)



# 4.4 48-lead LQFP and 48-pad QFN Pinout

Table 4-2. SAM7S32/16 Pinout<sup>(1)</sup>

1	ADVREF
2	GND
3	AD4
4	AD5
5	AD6
6	AD7
7	VDDIN
8	VDDOUT
9	PA17/PGMD5/AD0
10	PA18/PGMD6/AD1
11	PA19/PGMD7/AD2
12	PA20/AD3

13	VDDIO
14	PA16/PGMD4
15	PA15/PGMD3
16	PA14/PGMD2
17	PA13/PGMD1
18	VDDCORE
19	PA12/PGMD0
20	PA11/PGMM3
21	PA10/PGMM2
22	PA9/PGMM1
23	PA8/PGMM0
24	PA7/PGMNVALID

25	TDI
26	PA6/PGMNOE
27	PA5/PGMRDY
28	PA4/PGMNCMD
29	NRST
30	TST
31	PA3
32	PA2/PGMEN2
33	VDDIO
34	GND
35	PA1/PGMEN1
36	PA0/PGMEN0

37	TDO
38	JTAGSEL
39	TMS
40	TCK
41	VDDCORE
42	ERASE
43	VDDFLASH
44	GND
45	XOUT
46	XIN/PGMCK
47	PLLRC
48	VDDPLL

Note: 1. The bottom pad of the QFN package must be connected to ground.



## 5. Power Considerations

## 5.1 Power Supplies

The SAM7S Series has six types of power supply pins and integrates a voltage regulator, allowing the device to be supplied with only one voltage. The six power supply pin types are:

- VDDIN pin. It powers the voltage regulator and the ADC; voltage ranges from 3.0V to 3.6V, 3.3V nominal.
- VDDOUT pin. It is the output of the 1.8V voltage regulator.
- VDDIO pin. It powers the I/O lines and the USB transceivers; dual voltage range is supported. Ranges from 3.0V to 3.6V, 3.3V nominal or from 1.65V to 1.95V, 1.8V nominal. Note that supplying less than 3.0V to VDDIO prevents any use of the USB transceivers.
- VDDFLASH pin. It powers a part of the Flash and is required for the Flash to operate correctly; voltage ranges from 3.0V to 3.6V, 3.3V nominal.
- VDDCORE pins. They power the logic of the device; voltage ranges from 1.65V to 1.95V, 1.8V typical. It can be connected to the VDDOUT pin with decoupling capacitor. VDDCORE is required for the device, including its embedded Flash, to operate correctly.

During startup, core supply voltage (VDDCORE) slope must be superior or equal to 6V/ms.

VDDPLL pin. It powers the oscillator and the PLL. It can be connected directly to the VDDOUT pin.

No separate ground pins are provided for the different power supplies. Only GND pins are provided and should be connected as shortly as possible to the system ground plane.

In order to decrease current consumption, if the voltage regulator and the ADC are not used, VDDIN, ADVREF, AD4, AD5, AD6 and AD7 should be connected to GND. In this case VDDOUT should be left unconnected.

## 5.2 Power Consumption

The SAM7S Series has a static current of less than 60  $\mu$ A on VDDCORE at 25°C, including the RC oscillator, the voltage regulator and the power-on reset. When the brown-out detector is activated, 20  $\mu$ A static current is added.

The dynamic power consumption on VDDCORE is less than 50 mA at full speed when running out of the Flash. Under the same conditions, the power consumption on VDDFLASH does not exceed 10 mA.

## 5.3 Voltage Regulator

The SAM7S Series embeds a voltage regulator that is managed by the System Controller.

In Normal Mode, the voltage regulator consumes less than 100 µA static current and draws 100 mA of output current.

The voltage regulator also has a Low-power Mode. In this mode, it consumes less than 25  $\mu$ A static current and draws 1 mA of output current.

Adequate output supply decoupling is mandatory for VDDOUT to reduce ripple and avoid oscillations. The best way to achieve this is to use two capacitors in parallel: one external 470 pF (or 1 nF) NPO capacitor must be connected between VDDOUT and GND as close to the chip as possible. One external 2.2  $\mu$ F (or 3.3  $\mu$ F) X7R capacitor must be connected between VDDOUT and GND.

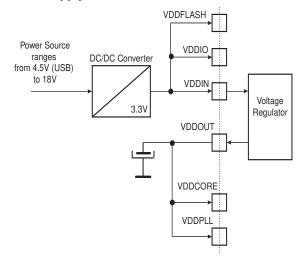
Adequate input supply decoupling is mandatory for VDDIN in order to improve startup stability and reduce source voltage drop. The input decoupling capacitor should be placed close to the chip. For example, two capacitors can be used in parallel: 100 nF NPO and  $4.7 \,\mu\text{F X7R}$ .

## 5.4 Typical Powering Schematics

The SAM7S Series supports a 3.3V single supply mode. The internal regulator is connected to the 3.3V source and its output feeds VDDCORE and the VDDPLL. Figure 5-1 shows the power schematics to be used for USB bus-powered systems.



Figure 5-1. 3.3V System Single Power Supply Schematic





## 6. I/O Lines Considerations

## 6.1 JTAG Port Pins

TMS, TDI and TCK are schmitt trigger inputs. TMS and TCK are 5-V tolerant, TDI is not. TMS, TDI and TCK do not integrate a pull-up resistor.

TDO is an output, driven at up to VDDIO, and has no pull-up resistor.

The JTAGSEL pin is used to select the JTAG boundary scan when asserted at a high level. The JTAGSEL pin integrates a permanent pull-down resistor of about 15 k $\Omega$  to GND, so that it can be left unconnected for normal operations.

## 6.2 Test Pin

The TST pin is used for manufacturing test, fast programming mode or SAM-BA Boot Recovery of the SAM7S Series when asserted high. The TST pin integrates a permanent pull-down resistor of about 15 k $\Omega$  to GND, so that it can be left unconnected for normal operations.

To enter fast programming mode, the TST pin and the PA0 and PA1 pins should be tied high and PA2 tied to low.

To enter SAM-BA Boot Recovery, the TST pin and the PA0, PA1 and PA2 pins should be tied high for at least 10 seconds. Then a power cycle of the board is mandatory.

Driving the TST pin at a high level while PA0 or PA1 is driven at 0 leads to unpredictable results.

#### 6.3 Reset Pin

The NRST pin is bidirectional with an open drain output buffer. It is handled by the on-chip reset controller and can be driven low to provide a reset signal to the external components or asserted low externally to reset the microcontroller. There is no constraint on the length of the reset pulse, and the reset controller can guarantee a minimum pulse length. This allows connection of a simple push-button on the pin NRST as system user reset, and the use of the signal NRST to reset all the components of the system.

The NRST pin integrates a permanent pull-up resistor to VDDIO.

## 6.4 ERASE Pin

The ERASE pin is used to re-initialize the Flash content and some of its NVM bits. It integrates a permanent pull-down resistor of about 15 k $\Omega$  to GND, so that it can be left unconnected for normal operations.

#### 6.5 PIO Controller A Lines

- All the I/O lines PA0 to PA31on SAM7S512/256/128/64/321 (PA0 to PA20 on SAM7S32) are 5V-tolerant and all integrate a programmable pull-up resistor.
- All the I/O lines PA0 to PA31 on SAM7S161 (PA0 to PA20 on SAM7S16) are not 5V-tolerant and all integrate a
  programmable pull-up resistor.

Programming of this pull-up resistor is performed independently for each I/O line through the PIO controllers.

5V-tolerant means that the I/O lines can drive voltage level according to VDDIO, but can be driven with a voltage of up to 5.5V. However, driving an I/O line with a voltage over VDDIO while the programmable pull-up resistor is enabled will create a current path through the pull-up resistor from the I/O line to VDDIO. Care should be taken, in particular at reset, as all the I/O lines default to input with the pull-up resistor enabled at reset.

#### 6.6 I/O Line Drive Levels

The PIO lines PA0 to PA3 are high-drive current capable. Each of these I/O lines can drive up to 16 mA permanently. The remaining I/O lines can draw only 8 mA.

However, the total current drawn by all the I/O lines cannot exceed 150 mA (100 mA for SAM7S32/16).





## 7. Processor and Architecture

## 7.1 ARM7TDMI Processor

- RISC processor based on ARMv4T Von Neumann architecture
  - Runs at up to 55 MHz, providing 0.9 MIPS/MHz
- Two instruction sets
  - ARM<sup>®</sup> high-performance 32-bit instruction set
  - Thumb<sup>®</sup> high code density 16-bit instruction set
- Three-stage pipeline architecture
  - Instruction Fetch (F)
  - Instruction Decode (D)
  - Execute (E)

## 7.2 Debug and Test Features

- Integrated EmbeddedICE<sup>™</sup> (embedded in-circuit emulator)
  - Two watchpoint units
  - Test access port accessible through a JTAG protocol
  - Debug communication channel
- Debug Unit
  - Two-pin UART
  - Debug communication channel interrupt handling
  - Chip ID Register
- IEEE1149.1 JTAG Boundary-scan on all digital pins

## 7.3 Memory Controller

- Bus Arbiter
  - Handles requests from the ARM7TDMI and the Peripheral DMA Controller
- Address decoder provides selection signals for
  - Three internal 1 Mbyte memory areas
  - One 256 Mbyte embedded peripheral area
- Abort Status Registers
  - Source, Type and all parameters of the access leading to an abort are saved
  - Facilitates debug by detection of bad pointers
- Misalignment Detector
  - Alignment checking of all data accesses
  - Abort generation in case of misalignment
- Remap Command
  - Remaps the SRAM in place of the embedded non-volatile memory
  - Allows handling of dynamic exception vectors
- Embedded Flash Controller
  - Embedded Flash interface, up to three programmable wait states
  - Prefetch buffer, buffering and anticipating the 16-bit requests, reducing the required wait states
  - Key-protected program, erase and lock/unlock sequencer
  - Single command for erasing, programming and locking operations
  - Interrupt generation in case of forbidden operation



#### **Peripheral DMA Controller** 7.4

- Handles data transfer between peripherals and memories
- Eleven channels: SAM7S512/256/128/64/321/161
- Nine channels: SAM7S32/16
  - Two for each USART
  - Two for the Debug Unit
  - Two for the Serial Synchronous Controller
  - Two for the Serial Peripheral Interface
  - One for the Analog-to-digital Converter
- Low bus arbitration overhead
  - One Master Clock cycle needed for a transfer from memory to peripheral
  - Two Master Clock cycles needed for a transfer from peripheral to memory
- Next Pointer management for reducing interrupt latency requirements
- Peripheral DMA Controller (PDC) priority is as follows (from the highest priority to the lowest):

Receive	DBGU	
Receive	USART0	
Receive	USART1	
Receive	SSC	
Receive	ADC	
Receive	SPI	
Transmit	DBGU	
Transmit	USART0	
Transmit	USART1	
Transmit	SSC	
Transmit	SPI	



## 8. Memories

## 8.1 SAM7S512

- 512 Kbytes of Flash Memory, dual plane
  - 2 contiguous banks of 1024 pages of 256 bytes
  - Fast access time, 30 MHz single-cycle access in Worst Case conditions
  - Page programming time: 6 ms, including page auto-erase
  - Page programming without auto-erase: 3 ms
  - Full chip erase time: 15 ms
  - 10,000 write cycles, 10-year data retention capability
  - 32 lock bits, protecting 32 sectors of 64 pages
  - Protection Mode to secure contents of the Flash
- 64 Kbytes of Fast SRAM
  - Single-cycle access at full speed

## 8.2 SAM7S256

- 256 Kbytes of Flash Memory, single plane
  - 1024 pages of 256 bytes
  - Fast access time, 30 MHz single-cycle access in Worst Case conditions
  - Page programming time: 6 ms, including page auto-erase
  - Page programming without auto-erase: 3 ms
  - Full chip erase time: 15 ms
  - 10,000 write cycles, 10-year data retention capability
  - 16 lock bits, protecting 16 sectors of 64 pages
  - Protection Mode to secure contents of the Flash
- 64 Kbytes of Fast SRAM
  - Single-cycle access at full speed

## 8.3 SAM7S128

- 128 Kbytes of Flash Memory, single plane
  - 512 pages of 256 bytes
  - Fast access time, 30 MHz single-cycle access in Worst Case conditions
  - Page programming time: 6 ms, including page auto-erase
  - Page programming without auto-erase: 3 ms
  - Full chip erase time: 15 ms
  - 10,000 write cycles, 10-year data retention capability
  - 8 lock bits, protecting 8 sectors of 64 pages
  - Protection Mode to secure contents of the Flash
- 32 Kbytes of Fast SRAM
  - Single-cycle access at full speed

## 8.4 SAM7S64

- 64 Kbytes of Flash Memory, single plane
  - 512 pages of 128 bytes



- Fast access time, 30 MHz single-cycle access in Worst Case conditions
- Page programming time: 6 ms, including page auto-erase
- Page programming without auto-erase: 3 ms
- Full chip erase time: 15 ms
- 10,000 write cycles, 10-year data retention capability
- 16 lock bits, protecting 16 sectors of 32 pages
- Protection Mode to secure contents of the Flash
- 16 Kbytes of Fast SRAM
  - Single-cycle access at full speed

## 8.5 SAM7S321/32

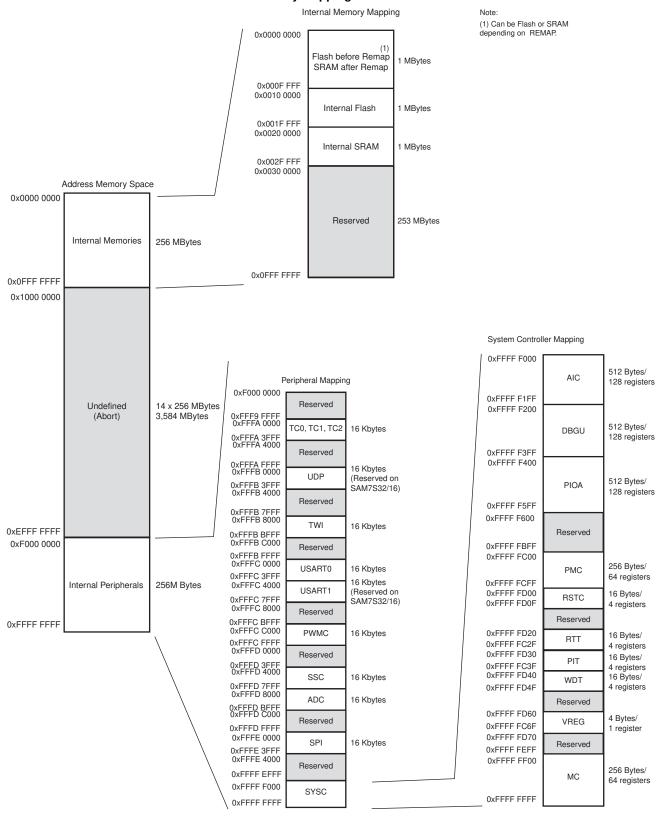
- 32 Kbytes of Flash Memory, single plane
  - 256 pages of 128 bytes
  - Fast access time, 30 MHz single-cycle access in Worst Case conditions
  - Page programming time: 6 ms, including page auto-erase
  - Page programming without auto-erase: 3 ms
  - Full chip erase time: 15 ms
  - 10,000 write cycles, 10-year data retention capability
  - 8 lock bits, protecting 8 sectors of 32 pages
  - Protection Mode to secure contents of the Flash
- 8 Kbytes of Fast SRAM
  - Single-cycle access at full speed

## 8.6 SAM7S161/16

- 16 Kbytes of Flash Memory, single plane
  - 256 pages of 64 bytes
  - Fast access time, 30 MHz single-cycle access in Worst Case conditions
  - Page programming time: 6 ms, including page auto-erase
  - Page programming without auto-erase: 3 ms
  - Full chip erase time: 15 ms
  - 10,000 write cycles, 10-year data retention capability
  - 8 lock bits, protecting 8 sectors of 32 pages
  - Protection Mode to secure contents of the Flash
- 4 Kbytes of Fast SRAM
  - Single-cycle access at full speed



Figure 8-1. SAM7S512/256/128/64/321/32/161/16 Memory Mapping





## 8.7 Memory Mapping

#### 8.7.1 Internal SRAM

- The SAM7S512 embeds a high-speed 64-Kbyte SRAM bank.
- The SAM7S256 embeds a high-speed 64-Kbyte SRAM bank.
- The SAM7S128 embeds a high-speed 32-Kbyte SRAM bank.
- The SAM7S64 embeds a high-speed 16-Kbyte SRAM bank.
- The SAM7S321 embeds a high-speed 8-Kbyte SRAM bank.
- The SAM7S32 embeds a high-speed 8-Kbyte SRAM bank.
- The SAM7S161 embeds a high-speed 4-Kbyte SRAM bank.
- The SAM7S16 embeds a high-speed 4-Kbyte SRAM bank

After reset and until the Remap Command is performed, the SRAM is only accessible at address 0x0020 0000. After Remap, the SRAM also becomes available at address 0x0.

#### 8.7.2 Internal ROM

The SAM7S Series embeds an Internal ROM. The ROM contains the FFPI and the SAM-BA program.

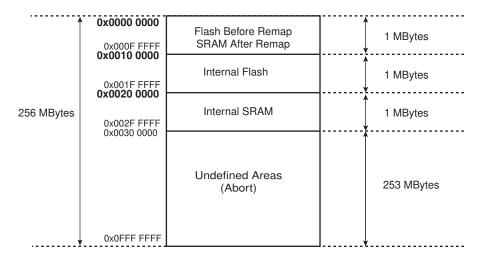
The internal ROM is not mapped by default.

#### 8.7.3 Internal Flash

- The SAM7S512 features two contiguous banks (dual plane) of 256 Kbytes of Flash.
- The SAM7S256 features one bank (single plane) of 256 Kbytes of Flash.
- The SAM7S128 features one bank (single plane) of 128 Kbytes of Flash.
- The SAM7S64 features one bank (single plane) of 64 Kbytes of Flash.
- The SAM7S321/32 features one bank (single plane) of 32 Kbytes of Flash.
- The SAM7S161/16 features one bank (single plane) of 16 Kbytes of Flash.

At any time, the Flash is mapped to address 0x0010 0000. It is also accessible at address 0x0 after the reset and before the Remap Command.

Figure 8-2. Internal Memory Mapping





## 8.8 Embedded Flash

#### 8.8.1 Flash Overview

- The Flash of the SAM7S512 is organized in two banks (dual plane) of 1024 pages of 256 bytes. The 524,288 bytes are organized in 32-bit words.
- The Flash of the SAM7S256 is organized in 1024 pages (single plane) of 256 bytes. The 262,144 bytes are organized in 32-bit words.
- The Flash of the SAM7S128 is organized in 512 pages (single plane) of 256 bytes. The 131,072 bytes are organized in 32-bit words.
- The Flash of the SAM7S64 is organized in 512 pages (single plane) of 128 bytes. The 65,536 bytes are organized in 32-bit words.
- The Flash of the SAM7S321/32 is organized in 256 pages (single plane) of 128 bytes. The 32,768 bytes are organized in 32-bit words.
- The Flash of the SAM7S161/16 is organized in 256 pages (single plane) of 64 bytes. The 16,384 bytes are organized in 32-bit words.
- The Flash of the SAM7S512/256/128 contains a 256-byte write buffer, accessible through a 32-bit interface.
- The Flash of the SAM7S64/321/32/161/16 contains a 128-byte write buffer, accessible through a 32-bit interface.

The Flash benefits from the integration of a power reset cell and from the brownout detector. This prevents code corruption during power supply changes, even in the worst conditions.

When Flash is not used (read or write access), it is automatically placed into standby mode.

#### 8.8.2 Embedded Flash Controller

The Embedded Flash Controller (EFC) manages accesses performed by the masters of the system. It enables reading the Flash and writing the write buffer. It also contains a User Interface, mapped within the Memory Controller on the APB. The User Interface allows:

- programming of the access parameters of the Flash (number of wait states, timings, etc.)
- starting commands such as full erase, page erase, page program, NVM bit set, NVM bit clear, etc.
- getting the end status of the last command
- getting error status
- programming interrupts on the end of the last commands or on errors

The Embedded Flash Controller also provides a dual 32-bit prefetch buffer that optimizes 16-bit access to the Flash. This is particularly efficient when the processor is running in Thumb mode.

Two EFCs are embedded in the SAM7S512 to control each bank of 256 Kbytes. Dual plane organization allows concurrent Read and Program. Read from one memory plane may be performed even while program or erase functions are being executed in the other memory plane.

One EFC is embedded in the SAM7S256/128/64/32/321/161/16 to control the single plane 256/128/64/32/16 Kbytes.



## 8.8.3 Lock Regions

#### 8.8.3.1 SAM7S512

Two Embedded Flash Controllers each manage 16 lock bits to protect 16 regions of the flash against inadvertent flash erasing or programming commands. The SAM7S512 contains 32 lock regions and each lock region contains 64 pages of 256 bytes. Each lock region has a size of 16 Kbytes.

If a locked-region's erase or program command occurs, the command is aborted and the LOCKE bit in the MC\_FSR register rises and the interrupt line rises if the LOCKE bit has been written at 1 in the MC\_FMR register.

The 16 NVM bits (or 32 NVM bits) are software programmable through the corresponding EFC User Interface. The command "Set Lock Bit" enables the protection. The command "Clear Lock Bit" unlocks the lock region.

Asserting the ERASE pin clears the lock bits, thus unlocking the entire Flash.

#### 8.8.3.2 SAM7S256

The Embedded Flash Controller manages 16 lock bits to protect 16 regions of the flash against inadvertent flash erasing or programming commands. The SAM7S256 contains 16 lock regions and each lock region contains 64 pages of 256 bytes. Each lock region has a size of 16 Kbytes.

If a locked-region's erase or program command occurs, the command is aborted and the LOCKE bit in the MC\_FSR register rises and the interrupt line rises if the LOCKE bit has been written at 1 in the MC\_FMR register.

The 16 NVM bits are software programmable through the EFC User Interface. The command "Set Lock Bit" enables the protection. The command "Clear Lock Bit" unlocks the lock region.

Asserting the ERASE pin clears the lock bits, thus unlocking the entire Flash.

#### 8.8.3.3 SAM7S128

The Embedded Flash Controller manages 8 lock bits to protect 8 regions of the flash against inadvertent flash erasing or programming commands. The SAM7S128 contains 8 lock regions and each lock region contains 64 pages of 256 bytes. Each lock region has a size of 16 Kbytes.

If a locked-region's erase or program command occurs, the command is aborted and the LOCKE bit in the MC\_FSR register rises and the interrupt line rises if the LOCKE bit has been written at 1 in the MC\_FMR register.

The 8 NVM bits are software programmable through the EFC User Interface. The command "Set Lock Bit" enables the protection. The command "Clear Lock Bit" unlocks the lock region.

Asserting the ERASE pin clears the lock bits, thus unlocking the entire Flash.

#### 8.8.3.4 SAM7S64

The Embedded Flash Controller manages 16 lock bits to protect 16 regions of the flash against inadvertent flash erasing or programming commands. The SAM7S64 contains 16 lock regions and each lock region contains 32 pages of 128 bytes. Each lock region has a size of 4 Kbytes.

If a locked-region's erase or program command occurs, the command is aborted and the LOCKE bit in the MC\_FSR register rises and the interrupt line rises if the LOCKE bit has been written at 1 in the MC\_FMR register.

The 16 NVM bits are software programmable through the EFC User Interface. The command "Set Lock Bit" enables the protection. The command "Clear Lock Bit" unlocks the lock region.

Asserting the ERASE pin clears the lock bits, thus unlocking the entire Flash.

#### 8.8.3.5 SAM7S321/32

The Embedded Flash Controller manages 8 lock bits to protect 8 regions of the flash against inadvertent flash erasing or programming commands. The SAM7S321/32 contains 8 lock regions and each lock region contains 32 pages of 128 bytes. Each lock region has a size of 4 Kbytes.

If a locked-region's erase or program command occurs, the command is aborted and the LOCKE bit in the MC\_FSR register rises and the interrupt line rises if the LOCKE bit has been written at 1 in the MC\_FMR register.



The 8 NVM bits are software programmable through the EFC User Interface. The command "Set Lock Bit" enables the protection. The command "Clear Lock Bit" unlocks the lock region.

Asserting the ERASE pin clears the lock bits, thus unlocking the entire Flash.

#### 8.8.3.6 SAM7S161/16

The Embedded Flash Controller manages 8 lock bits to protect 8 regions of the flash against inadvertent flash erasing or programming commands. The SAM7S161/16 contains 8 lock regions and each lock region contains 32 pages of 64 bytes. Each lock region has a size of 2 Kbytes.

If a locked-region's erase or program command occurs, the command is aborted and the LOCKE bit in the MC\_FSR register rises and the interrupt line rises if the LOCKE bit has been written at 1 in the MC\_FMR register.

The 8 NVM bits are software programmable through the EFC User Interface. The command "Set Lock Bit" enables the protection. The command "Clear Lock Bit" unlocks the lock region.

Asserting the ERASE pin clears the lock bits, thus unlocking the entire Flash.

Table 8-1 summarizes the configuration of the eight devices.

Table 8-1. Flash Configuration Summary

Device	Number of Lock Bits	Number of Pages in the Lock Region	Page Size
SAM7S512	32	64	256 bytes
SAM7S256	16	64	256 bytes
SAM7S128	8	64	256 bytes
SAM7S64	16	32	128 bytes
SAM7S321/32	8	32	128 bytes
SAM7S161/16	8	32	64 bytes

## 8.8.4 Security Bit Feature

The SAM7S Series features a security bit, based on a specific NVM Bit. When the security is enabled, any access to the Flash, either through the ICE interface or through the Fast Flash Programming Interface, is forbidden. This ensures the confidentiality of the code programmed in the Flash.

This security bit can only be enabled, through the Command "Set Security Bit" of the EFC User Interface. Disabling the security bit can only be achieved by asserting the ERASE pin at 1, and after a full flash erase is performed. When the security bit is deactivated, all accesses to the flash are permitted.

It is important to note that the assertion of the ERASE pin should always be longer than 50 ms.

As the ERASE pin integrates a permanent pull-down, it can be left unconnected during normal operation. However, it is safer to connect it directly to GND for the final application.

#### 8.8.5 Non-volatile Brownout Detector Control

Two general purpose NVM (GPNVM) bits are used for controlling the brownout detector (BOD), so that even after a power loss, the brownout detector operations remain in their state.

These two GPNVM bits can be cleared or set respectively through the commands "Clear General-purpose NVM Bit" and "Set General-purpose NVM Bit" of the EFC User Interface.

- GPNVM Bit 0 is used as a brownout detector enable bit. Setting the GPNVM Bit 0 enables the BOD, clearing it
  disables the BOD. Asserting ERASE clears the GPNVM Bit 0 and thus disables the brownout detector by default.
- The GPNVM Bit 1 is used as a brownout reset enable signal for the reset controller. Setting the GPNVM Bit 1
  enables the brownout reset when a brownout is detected, Clearing the GPNVM Bit 1 disables the brownout reset.
  Asserting ERASE disables the brownout reset by default.



#### 8.8.6 Calibration Bits

Eight NVM bits are used to calibrate the brownout detector and the voltage regulator. These bits are factory configured and cannot be changed by the user. The ERASE pin has no effect on the calibration bits.

## 8.9 Fast Flash Programming Interface

The Fast Flash Programming Interface allows programming the device through either a serial JTAG interface or through a multiplexed fully-handshaked parallel port. It allows gang-programming with market-standard industrial programmers.

The FFPI supports read, page program, page erase, full erase, lock, unlock and protect commands.

The Fast Flash Programming Interface is enabled and the Fast Programming Mode is entered when the TST pin and the PA0 and PA1 pins are all tied high and PA2 is tied low.

## 8.10 SAM-BA Boot Assistant

The SAM-BA® Boot Recovery restores the SAM-BA Boot in the first two sectors of the on-chip Flash memory. The SAM-BA Boot recovery is performed when the TST pin and the PA0, PA1 and PA2 pins are all tied high for 10 seconds. Then, a power cycle of the board is mandatory.

The SAM-BA Boot Assistant is a default Boot Program that provides an easy way to program in situ the on-chip Flash memory.

The SAM-BA Boot Assistant supports serial communication through the DBGU or through the USB Device Port. (The SAM7S32/16 have no USB Device Port.)

- Communication through the DBGU supports a wide range of crystals from 3 to 20 MHz via software autodetection.
- Communication through the USB Device Port is limited to an 18.432 MHz crystal. (

The SAM-BA Boot provides an interface with SAM-BA Graphic User Interface (GUI).

# 9. System Controller

The System Controller manages all vital blocks of the microcontroller: interrupts, clocks, power, time, debug and reset.

The System Controller peripherals are all mapped to the highest 4 Kbytes of address space, between addresses 0xFFFF F000 and 0xFFFF FFFF.

Figure 9-1 on page 26 and Figure 9-2 on page 27 show the product specific System Controller Block Diagrams.

Figure 8-1 on page 20 shows the mapping of the of the User Interface of the System Controller peripherals. Note that the memory controller configuration user interface is also mapped within this address space.

